



ALLIANCE MEMORY MDS REPORT

Part Number:			AS4C32M16SB-7BIN						
Part Weight:			129.687mg						
No .	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM
1	Substrate	HL-8320NX-A / AUS 308	35.728	Barium Sulfate	7727-43-7	1.98%	2.572	7.20%	71974
				Dipropylene glycolmonomethyl ether	34590-94-8	1.06%	1.371	3.84%	38386
				Talc containing noasbestiform fibers	14807-96-6	0.18%	0.229	0.64%	6398
				Epoxy resin	Trade seacret	0.97%	1.257	3.52%	35187
				Morpholine derivative	Trade seacret	0.18%	0.229	0.64%	6398
				Naphthalene	91-20-3	0.04%	0.057	0.16%	1599
				Cured thermosetting resin (including inorganic filler)	Trade Secret	6.90%	8.953	25.06%	250578
				Continuous Filament Fiber Glass	Trade Secret	4.60%	5.969	16.71%	167052
				Cu Foil	7440-50-8	2.20%	2.857	8.00%	79972
				Au Plating	7440-57-5	0.04%	0.057	0.16%	1599
				Ni Plating	7440-02-0	0.33%	0.432	1.21%	12085
				Cu Plating	7440-50-8	9.06%	11.747	32.88%	328772
2	Mold compound	G1250	69.175	Silica(Fused)	60676-86-0	45.87%	59.491	86.00%	860000
				Epoxy resin	Trade Secret	3.63%	4.704	6.80%	68000
				Phenol Resin	Trade Secret	3.68%	4.773	6.90%	69000
				Carbon Black	1333-86-4	0.16%	0.208	0.30%	3000
3	Epoxy	2025D	0.48	Silica, amorphous, treated	68909-20-6	0.14%	0.182	38.00%	380000
				Fatty acids, C18-unsatd., dimers, hydrogenated, di-Me esters, hydrogenated, bis(2,5-dihydro-2,5-dioxo-1H-pyrrole-1-hexanoate)	Trade Secret	0.10%	0.134	28.00%	280000
				Silicon dioxide	7631-86-9	0.06%	0.077	16.00%	160000
				2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9	0.03%	0.038	8.00%	80000
				A mixture of: 4-allyl-2,6-bis(2,3-epoxypropyl)phenol; 4-allyl-6-[3-[6-[3-[3-(4-allyl-2,6-bis(2,3-epoxypropyl)phenoxy)-2-hydroxyp	Trade Secret	0.03%	0.038	8.00%	80000
				Epichlorohydrin-4,4'-isopropylidene diphenol resin	25068-38-6	0.00%	0.003	0.70%	7000
				3-Trimethoxysilylpropyl methacrylate	2530-85-0	0.00%	0.003	0.60%	6000
2-Ethyl-4-methyl-1H-imidazole-1-propionitrile	23996-25-0	0.00%	0.003	0.70%	7000				
4	Solder ball	Sn3Ag0.5Cu	15.498	Tin	7440-31-5	11.47%	14.878	96.00%	960000
				Silver	7440-22-4	0.36%	0.465	3.00%	30000
				Copper	7440-50-8	0.12%	0.155	1.00%	10000
5	Gold wire	Au	0.35	Gold	7440-57-5	0.27%	0.350	100.00%	1000000
6	Die	Chip	8.456	Silicon	7440-21-3	6.39%	8.286	98.00%	980000
				Aluminum	7429-90-5	0.13%	0.169	2.00%	20000

129.687

100.00%

129.687

600.00%

6000000